

# Product Change Notification - SIGE000012 - JAON-29XUTR452

Date:

17 Jun 2020

**Product Category:** 

Clock and Timing - Clock and Data Distribution

**Affected CPNs:** 



### **Notification subject:**

CCB 2871 Final Notice: Release to production of listed Micrel Clock and Timing product type manufactured with the SiGe process technology to Fabrication site (FAB 5).

#### **Notification text:**

#### **PCN Status:**

Final notification

Note: This final PCN only pertains to the products listed in this PCN. Additional final PCNs may be issued for this combination of product type and process technology.

# **PCN Type:**

Manufacturing Change

## **Microchip Parts Affected:**

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

## **Description of Change:**

Release to production of listed Micrel Clock and Timing product type manufactured with the SiGe process technology to Fabrication site (FAB 5).

## Pre Change:

Fabricated at Micrel fabrication site (San Jose, CA, USA) (SJ) using 6 inch wafers.

## **Post Change:**

Fabricated at Atmel Fabrication site FAB 5 (Colorado Springs, CO, USA) (COS) using 6 inch wafers

Pre and Post Change Summary:

Pre and Post Change Summary:  Pre Change Post Change								
	Pre Change							
		Primary Fab Location:	Secondary Fab					
	Microl Fobrication Cita		Location:					
Fabrication Location	Micrel Fabrication Site	Atmel Fabrication site						
	(San Jose, CA, USA)	FAB 5 (Colorado	Microchip Fabrication					
		Springs, CO USA)	Site (Tempe, AZ USA)					
Wafer Diameter	6 inches (150 mm)	6 inches (150 mm)	8 inches (200 mm)					
Quality certification	ISO9001	ISO9001/TS16949	ISO/TS16949					
Data sheet /	No Chango	No Changa	No Chango					
specifications	No Change	No Change	No Change					
Design/layout	No Change	No Change	No Change					
Die Size	No change	No change	No change					
Final test program	No change	No change	No change					
Package Type/MSL	No Change	No Change	No Change					

Impacts to Data Sheet:

No impact anticipated.

**Change Impact:** 

None

**Reason for Change:** 



To improve productivity with the closure of the Micrel fab (SJ) as part of the integration of Micrel and Microchip.

## **Change Implementation Status:**

In Progress

#### **Estimated First Ship Date:**

Estimated First Ship Date (EFSD) are identified for each catalog part numbers (CPN) listed in the attached parts list. This can be found in the attachments field below labeled as PCN\_#\_Affected\_CPN.

**Summary Time Table of notable events to date:** 

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		Mar	ch 2	2017			J	uly	201	7			Ju	ıne 202	20	
Workweek	09	10	11	12	13	۸	27	28	29	30	^	23	24	25	26	27
Initial PCN Issue					Х											
Date																
Qualification Report																
Availability and																
Intermediate PCN							lχ									
issue date							^									
JAON-29XUTR452																
Final PCN Issue																
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JAON-29XUTR452																
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Estimated First																attach
Ship Date																ed
																parts
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																below

## **Method to Identify Change:**

Traceability code.

## **Qualification Report:**

Please open the attachments included with this PCN labeled as PCN\_#\_Qual Report.

### **Revision History:**

March 30, 2017: Issued initial notification.

July 5, 2017: Issued intermediate notification. Attached the Qualification report.

**June 17, 2020:** Issued final notification as PCN number JAON-29XUTR452 - SIGE000012 for listed Micrel's Clock and Timing products manufactured with the SiGe process technology to Fabrication site (FAB 5). Provided estimated first ship date (EFSD) for each CPN listed in the attached parts list. The change described in this PCN does not alter Micrel's or Atmel's or Microchip's current regulatory compliance regarding the material content of the applicable products.

## Attachment(s):

PCN\_JAON-29XUTR452-SIGE000012 Qual\_Report.pdf PCN\_JAON-29XUTR452-SIGE000012 Affected CPN.pdf PCN\_JAON-29XUTR452-SIGE000012 Affected CPN.xls



Please contact your local <u>Microchip sales office</u> with questions or concerns regarding this notification.

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If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

JAON-29XUTR452 - CCB 2871 Final Notice: Release to production of listed Micrel Clock and Timing product type manufactured with the SiGe process technology to Fabrication site (FAB 5).

Affected Catalog Part Numbers (CPN)

SY58600UMG-TR

SY58602UMG-TR

SY56020XRMG

SY56216RMG

SY56216RMG-TR

SY56020XRMG-TR

SY58025UMG

SY58030UMG

SY58025UMG-TR

SY58030UMG-TR

Date: Wednesday, June 17, 2020

JAON-29XUTR452-SIGE000012 - CCB 2871 Final Notice: Release to production of listed Micrel Clock and Timing product type manufactured with the SiGe process technology to Fabrication site (FAB 5).

Affected Catalog Part Numbers (CPN)

PCN_JAON-29XUTR452-SIGE000012							
CATALOG_PART_NBR	Estimated First Ship Date(EFSD)						
SY58600UMG-TR	June 30, 2020						
SY58602UMG-TR	June 30, 2020						
SY56020XRMG	June 30, 2020						
SY56216RMG	June 30, 2020						
SY56216RMG-TR	June 30, 2020						
SY56020XRMG-TR	June 30, 2020						
SY58025UMG	June 30, 2020						
SY58030UMG	June 30, 2020						
SY58025UMG-TR	June 30, 2020						
SY58030UMG-TR	June 30, 2020						



# **QUALIFICATION REPORT SUMMARY**

PCN #: JAON-29XUTR452 - SIGE000012

Date **June 1, 2017** 

Qualification of Fabrication site (FAB 5) for Micrel products manufactured with the SiGe process technology.

PART NUMBER / MASK	PACKAGE TYPE	ASSEMBLY LOCATION	FAB LOCATION	PROCESS NAME
SY58023UMG / 2D602	QFN33-16L	UNISEM, IPOH MALAYSIA	MICROCHIP FAB-5 Colorado Springs	S2_SiGe 0.6u

TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	FAB LOT ID.	168 HR Rej/ss	408 HR Rej/ss	COMMENTS
HTOL	JESD22, Method 108	1645E3C	FA23647B	0/80	0/80	
High Temperature Operating Life Test	Tj = +135°C	1651CKW	A6Y2057	0/82	0/82	
	Ta = +85°C					
	Vcc = +3.10V					
HTOL	JESD22, Method 108	1651CKW	A6Y2057	0/82	0/82	
High Temperature Operating Life Test	Tj = +150°C	1703PVQ	6Y2092	0/82	0/82	
	Ta = +105°C					
	Vcc = +3.10V					

## ELECTROSTATIC DISCHARGE AND LATCH-UP

TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	FAB LOT ID.	STRESS	RESULT Rej/ss	COMMENTS
ESD-HBM  Human Body Model ATE Test @ Room +25C	R= 1500 Ohms C= 100 pF 1X +/- Voltage	N/A	7U2874	+/-500V	0/3	Note: ESD ratings are, device specific. All products, qualified on the 6" Micrel, process technologies at, Microchip Fabs will have the, same or better ESD and, Latch-up performance as the 6" products fabricated at San Jose wafer fabrication site.
ESD-CDM Charged Device Model ATE Test @ Room +25C	JESD22-C101 1X +/- Voltage	1703PVQ	6Y2092	+/-250V +/-500V +/-750V +/-1000V +/-1500V	0/3 0/3 0/3 0/3 0/3 0/3	
TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	LOT ID.	STRESS	RESULT Rej/ss	COMMENTS
LATCH-UP	JESD-78 A = +25°C	1651CKW 1645E3C	A6Y2057 FA23647B	I/O LU O/V LU	0/6 0/6	

PACKAGE QUALIFI	CATION RESOLTS					
TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	ASSEM LOT ID.	Rej/ss		COMMENTS
Level 1 Pre-conditioning Flow	JESD22-A113	1651CKW	UNIS173900097.000	0/330		
Use samples to perform		1703PVQ	UNIS174300114.000	0/310		
PPOT/HAST/TCY						
TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	ASSEM LOT ID.	96 HR Rej/ss		COMMENTS
uHAST	JESD22-A118	1651CKW	UNIS173900097.000	0/82		
With Level 1 Pre- conditioning	Ta= +130°C/85%RH	1703PVQ	UNIS174300114.000	0/82		
Tpeak + 260°C 3X Reflow						
TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	ASSEM LOT ID.	96 HR Rej/ss		COMMENTS
HAST	JESD22-A110 (BIASED)	1651CKW	UNIS173900097.000	0/80		
With Level 1 Pre- conditioning	Ta= +130°C/85%RH	1703PVQ	UNIS174300114.000	0/80		
Tpeak + 260°C 3X Reflow	Vcc = +1.2V					
TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	ASSEM LOT ID.	500 CY Rej/ss	1000 CY Rej/ss	COMMENTS
TEMP CYCLE	JESD22-A104	1651CKW	UNIS173900097.000	0/82	0/82	
With Level 1 Pre- conditioning Tpeak + 260°C 3X Reflow	Ta = -65°C / +150°C	1703PVQ	UNIS174300114.000	0/82	0/82	
TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	ASSEM LOT ID.	<b>1000 HR</b> Rej/ss	COMME	NTS
HTSL	JESD22-A103	1651CKW	UNIS173900097.000	0/50		
High Temperature Storage Life	Ta = +150°C	1703PVQ	UNIS174300114.000	0/50		
FLAMMABILITY	UL-94V-0 Certified	material flamm	bunds used by Micrel meet the ability certifications. Micrel reverify the certifications on the	equires a Cer		